

**AMENDMENTS TO THE CLAIMS**

Claim 1. (canceled)

2. (previously presented) The imaging device of claim 7, wherein said photosensitive elements are arranged in a two-dimensional array.

3. (previously presented) The imaging device of claim 7, wherein said transparent material includes injection molded epoxy resin.

4. (currently amended) The imaging device of claim 7, further comprising leads connected to said semiconductor imaging chip, said leads being partially encapsulated in said transparent material.

Claims 5-6. (canceled)

7. (currently amended) An imaging device, comprising:

a frame having a support structure, ~~said support structure supporting;~~

a semiconductor imaging chip supported by said support structure, [[:]] said semiconductor imaging chip having an array of photosensitive elements configured to receive ~~for receiving~~ an image and ~~for generating~~ generate a plurality of corresponding image signals[[:]];

a package encapsulating said frame, support structure, and semiconductor imaging chip ~~encapsulated~~ in a transparent material, said transparent material ~~having~~ covering said chip, said photosensitive elements receiving said image through said transparent material; and

an optical light transmitting device ~~covering~~ supported in line with an image being received by said photosensitive elements of said semiconductor imaging chip.

8. (previously presented) The imaging device of claim 7, wherein said optical light transmitting device is formed of said transparent material.

9. (currently amended) The imaging device of claim 7 wherein said optical light transmitting device is a color filter, said filter being formed by color tinting of said transparent material.

10. (currently amended) The imaging device of claim 7, further comprising a color filter array molded into and encased by said transparent material.

11. (currently amended) An imaging system, comprising:

a system for transmitting an image including an image source ~~and a first semiconductor device~~, said image source being arranged to transmit the capable of simultaneously transmitting an image to simultaneously onto each of a plurality of imaging semiconductor devices;

wherein each of said plurality of ~~semiconductor~~ imaging devices includes ~~first, second and third a semiconductor devices~~ device including an array of photosensitive elements, each semiconductor device being mounted on a respective frames frame, each of said frames having a support structure, each of said ~~first, second, and third~~ semiconductor devices receiving said image and generating corresponding signals; and

wherein each ~~of~~ said frame, support structure, and respective semiconductor device is encapsulated in a respective first, second and third packages package for protecting and supporting each said ~~first, second and third semiconductor devices~~

device, each of said packages being formed of transparent material, said transparent material including injection molded resin for transmitting ~~an~~ the image from said image source onto said ~~first, second and third~~ semiconductor devices.

12. (original) The system of claim 11, wherein said image source includes a lens.

13. (currently amended) The system of claim 11 wherein said ~~first, second and third~~ semiconductor imaging devices include complementary color filters.

14. (currently amended) The system of claim 13, wherein said complementary color filters are molded into said ~~first, second and third~~ packages.

15. (currently amended) The system of claim 13, wherein said ~~first, second and third~~ packages include red, green and blue filters.

16. (currently amended) The system of claim 13, wherein said ~~first, second and third~~ packages include cyan, magenta and yellow filters.

Claims 17-27. (canceled)

28. (currently amended) An imaging device, comprising:

a housing having a cavity and a bottom surface;

a semiconductor imaging chip located within said cavity of said housing, said semiconductor imaging chip including an array of photosensitive elements ~~for receiving~~ configured to receive an image and ~~for generating~~ generate corresponding signals, said photosensitive elements being covered by a transparent cover;

said semiconductor imaging chip being encapsulated in a transparent material, wherein said transparent material has an uppermost surface substantially planar to an uppermost surface of said housing; and

an optical light transmitting device ~~covering~~ supported in line with an image being received by said photosensitive elements.

29. (previously presented) The device of claim 28, wherein said transparent cover includes a color filter.

Claim 30. (canceled)

31. (previously presented) The imaging device of claim 28, wherein said housing is formed of molded plastic.

32. (previously presented) The imaging device of claim 7, wherein said optical light transmitting device is a lens, said lens being formed of said transparent material.

33. (previously presented) The imaging device of claim 28, wherein said housing is formed of a ceramic material.

34. (new) The imaging device of claim 7, wherein said optical light transmitting device is a color filter, said color filter being supported separate from said package of said transparent material.